

Title (en)
ETCHING SOLUTION

Title (de)
ÄTZLÖSUNG

Title (fr)
SOLUTION D'ATTAQUE

Publication
EP 0536362 B1 19960703 (DE)

Application
EP 92908839 A 19920421

Priority
• DE 9200321 W 19920421
• DE 4113283 A 19910424

Abstract (en)
[origin: WO9219792A1] An etching solution for removing a metallic layer from a substrate contains a hydrogenated compound that dissolves the metal itself while evolving hydrogen and a nitro-substituted organic compound. The solution is characterized by the fact that the selected nitro-substituted organic compound is a compound having an easily hydrogenizable nitro group.

IPC 1-7
C23F 1/44

IPC 8 full level
C23F 1/10 (2006.01); **C23F 1/20** (2006.01); **C23F 1/26** (2006.01); **C23F 1/28** (2006.01); **C23F 1/36** (2006.01); **C23F 1/44** (2006.01)

CPC (source: EP US)
C23F 1/10 (2013.01 - EP US); **C23F 1/20** (2013.01 - EP US); **C23F 1/26** (2013.01 - EP US); **C23F 1/28** (2013.01 - EP US);
C23F 1/36 (2013.01 - EP US); **C23F 1/44** (2013.01 - EP US)

Citation (examination)
METAL FINISHING Bd. 89, Nr. 1A, Januar 1991, Seiten 388-396; STANLEY HIRSCH: 'stripping metallic coatings' siehe Seite 392-Seite 394

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EP 0536362 A1 19930414; EP 0536362 B1 19960703; JP H06500363 A 19940113; US 5462640 A 19951031

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